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### FDD5612

## 60V N-Channel PowerTrench® MOSFET

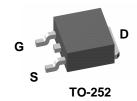
#### **General Description**

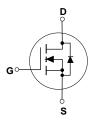
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable  $R_{\text{DS(ON)}}$  specifications. The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

#### **Features**

- 18 A, 60 V.  $R_{DS(ON)} = 55 \ m\Omega \ @ \ V_{GS} = 10 \ V$   $R_{DS(ON)} = 64 \ m\Omega \ @ \ V_{GS} = 6 \ V$
- Optimized for use in high frequency DC/DC converters.
- · Low gade charge.
- · Very fast switching.





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage		60	V
$V_{GSS}$	Gate-Source Voltage		±20	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1)	18	А
		(Note 1a)	5.4	
	Drain Current - Pulsed		100	
P <sub>D</sub>	Maximum Power Dissipation	(Note 1)	42	W
		(Note 1a)	3.8	
		(Note 1b)	1.6	
$T_J$ , $T_{STG}$	Operating and Storage Junction Temperature Range		-55 to +175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	3.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	40	°C/W
		(Note 1b)	96	

**Package Marking and Ordering Information** 

Device Marking	Device	Reel Size	Tape width	Quantity
FDD5612	FDD5612	13"	16mm	2500 units

Symbol	Parameter	Test Conditions		Тур	Max	Units
Drain-So	ource Avalanche Ratings (Note	1)			I.	
W <sub>DSS</sub>	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 30 \text{ V}, \qquad I_{D} = 5.4 \text{ A}$			90	mJ
I <sub>AR</sub>	Maximum Drain-Source Avalanche Current				5.4	А
Off Char	acteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	60			V
ΔBV <sub>DSS</sub> ΔT <sub>.1</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		62		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 48 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			1	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage, Forward	$V_{GS} = 20 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage, Reverse	V <sub>GS</sub> = -20 V V <sub>DS</sub> = 0 V			-100	nA
On Char	acteristics (Note 2)					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	1	2.4	3	V
$\Delta V_{GS(th)}$ $\Delta T_{.1}$	Gate Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		-6		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	$\begin{array}{lll} V_{GS} = 10 \; V, & I_D = 5.4 \; A \\ V_{GS} = 6 \; V, & I_D = 5 \; A \\ V_{GS} = 10 \; V, \; I_D = 5.4 \; A, \; T_J = 125 ^{\circ} C \end{array}$		36 42 64	55 64 103	mΩ
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 5 \text{ V}$	20			Α
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, \qquad I_{D} = 5.4 \text{ A}$		15		S
Dvnamic	Characteristics					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 30 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		660		pF
Coss	Output Capacitance	f = 1.0 MHz		79		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1.0 WH 12		36		pF
Switchin	g Characteristics (Note 2)					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, \qquad I_{D} = 1 \text{ A},$		8	16	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		4	8	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			24	38	ns
t <sub>f</sub>	Turn–Off Fall Time			4	8	ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS} = 30 \text{ V}, \qquad I_{D} = 5.4 \text{ A},$		7.5	11	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{GS} = 10 \text{ V}$		2.5		nC
Q <sub>gd</sub>	Gate-Drain Charge			3		nC
Drain-So	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain-Source	Diode Forward Current			2.7	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_S = 2.7 \text{ A}  \text{(Note 2)}$		0.8	1.2	V

 $R_{\theta JA}$  is the guaranteed design while  $R_{\theta JA}$  is determined by the user's design.  $R_{\theta JA}$  has been used to determine some of the maximum ratings.





b)  $R_{\theta JA} = 96^{O} \text{C/W}$  when mounted on a 0.076 in pad of 2oz copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

<sup>1.</sup> R<sub>QJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the drain tab.

#### **Typical Characteristics**

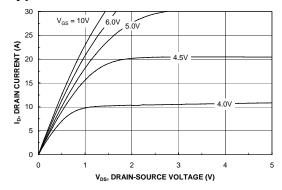


Figure 1. On-Region Characteristics.

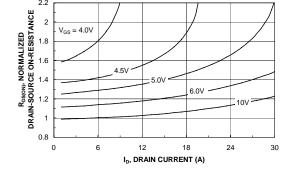


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

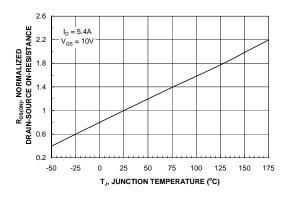


Figure 3. On-Resistance Variation with Temperature.

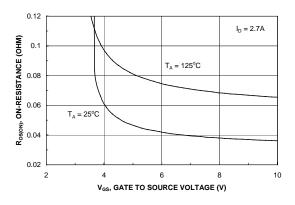


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

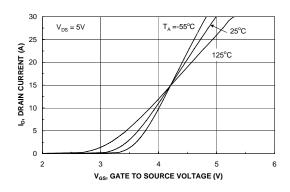


Figure 5. Transfer Characteristics.

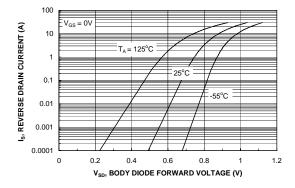
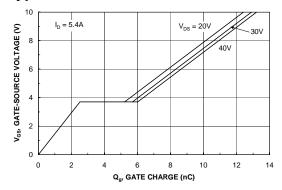


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

#### **Typical Characteristics**



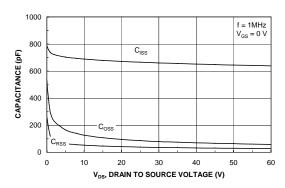
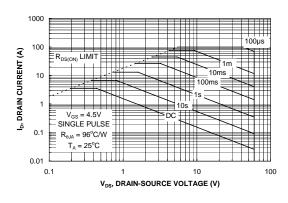


Figure 7. Gate Charge Characteristics.





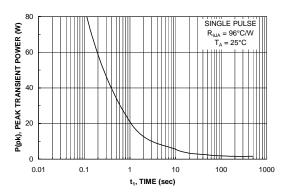


Figure 9. Maximum Safe Operating Area.



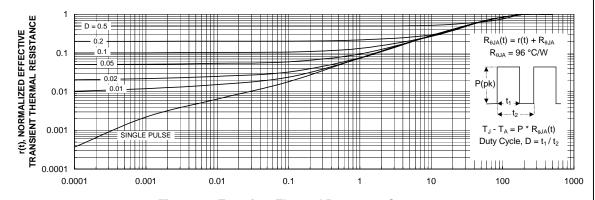


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



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